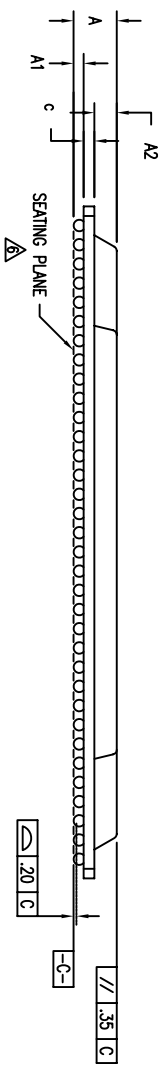
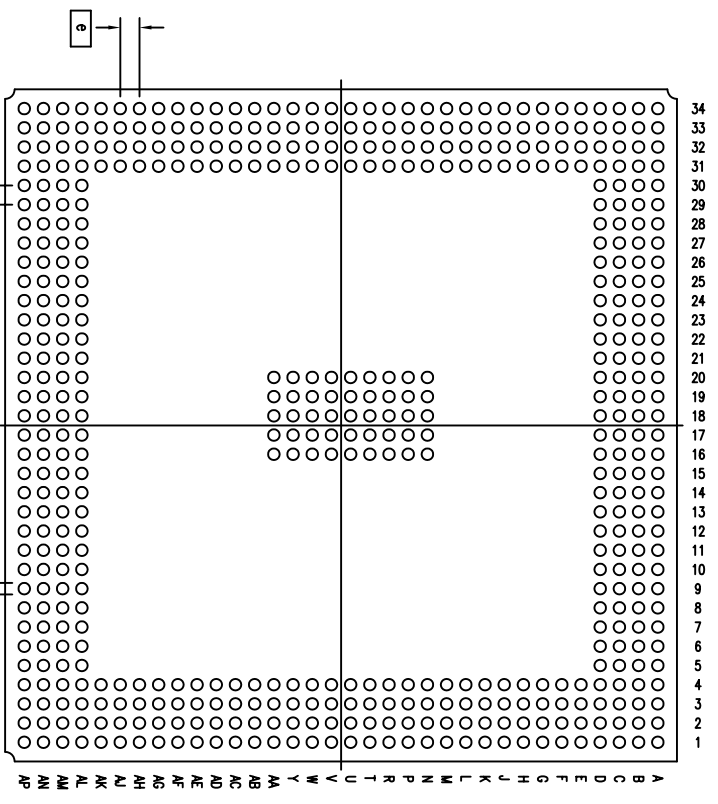
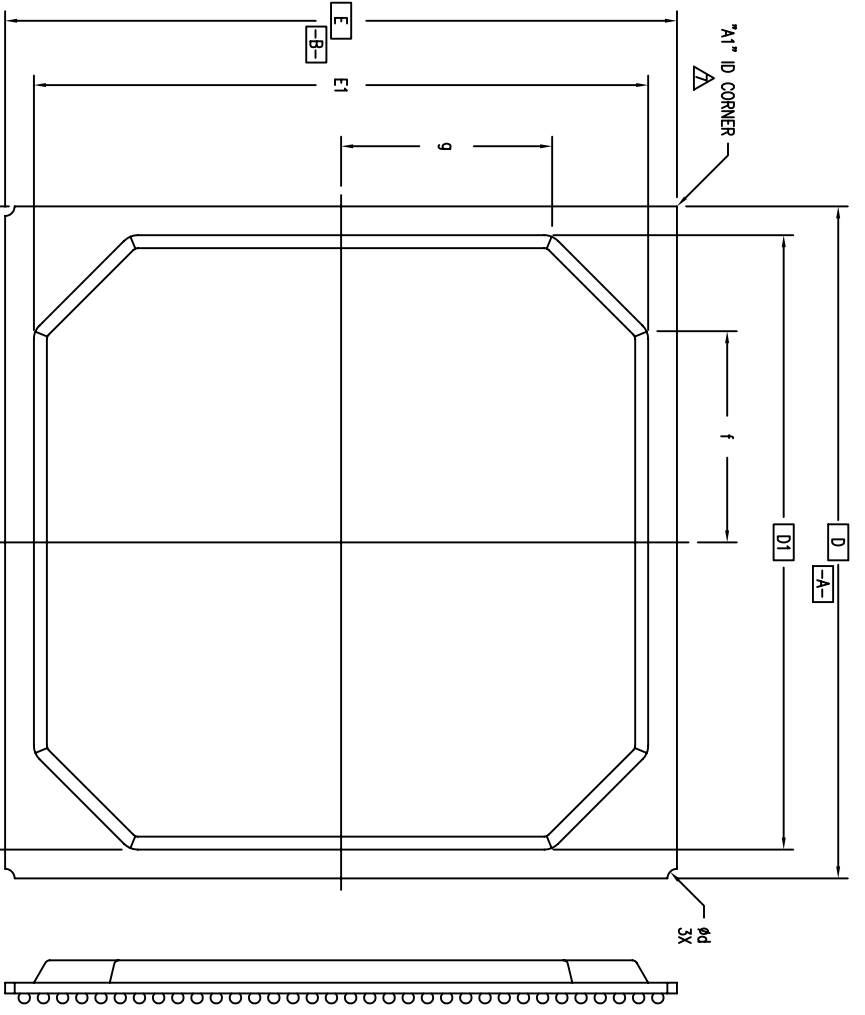


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	PRELIMINARY RELEASE	05/05/02	TJ VJ
01	ADDED GREEN BBG	06/22/09	P.Park
02	COMBINE POD & LAND PATTERN	06/07/13	KS



TOLERANCES UNLESS SPECIFIED

DECIMAL ANGULAR

XXXX ±

XXXX ±

XXXX ±

APPROVALS DATE

DRAWN 9/1 05/05/02

CHECKED

IDT Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138
PHONE: (408) 284-8245
FAX: (408) 284-8591
TWC: 910-338-2070

W.W.W. IDT, COIL FAX

TITLE BB/BBG 525 PACKAGE OUTLINE
35.0 X 35.0 mm BODY PBGA
1.00 mm BALL PITCH

SIZE C DRAWING No. PSC-4112

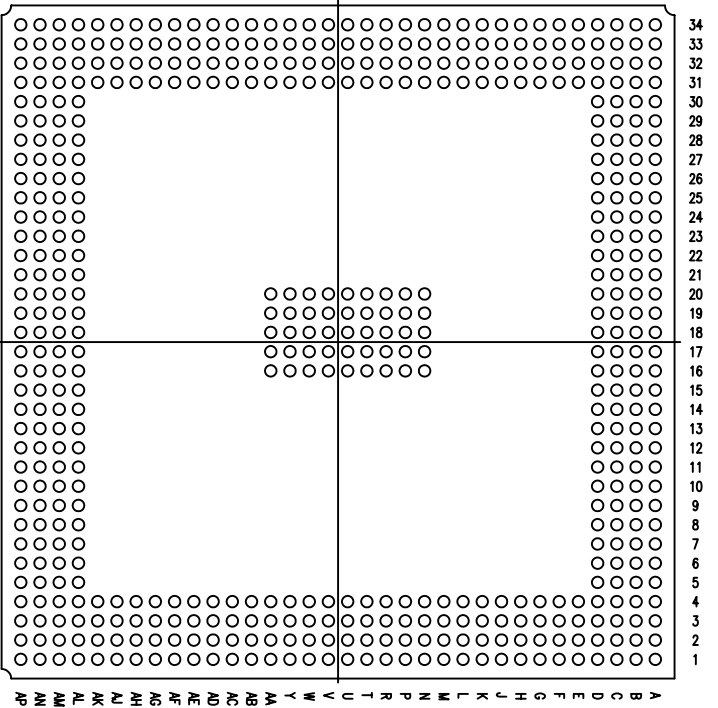
DO NOT SCALE DRAWING

SHEET 1 OF 3


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	PRELIMINARY RELEASE	05/05/02	TU VU
01	ADDED GREEN BSG	06/22/09	P-Park
02	COMBINE POD & LAND PATTERN	06/07/13	KS

NOTES:

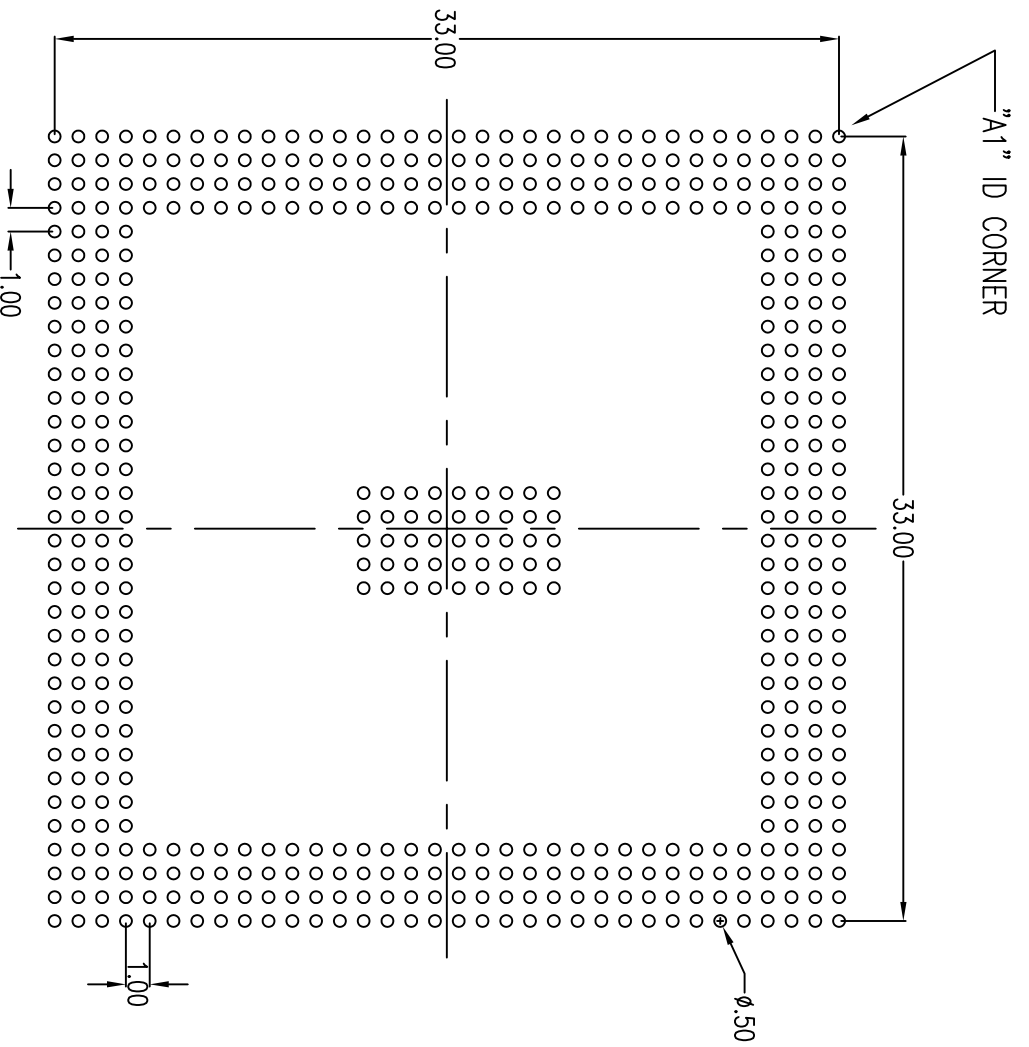
- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- 2 "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH
- 3 "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE
- 4 "N" REPRESENTS THE BALLCOUNT NUMBER
- 5 DIMENSION "p" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square -C-
- 6 SEATING PLANE AND PRIMARY DATUM \square -C- ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
- 7 "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON TOP SURFACE OF PACKAGE
- 8 ALL DIMENSIONS ARE IN MILLIMETERS
- 9 THIS DRAWING CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-043, VARIATION AAR-1



SYMBOL	JEDEC VARIATION			NOTE
	MIN	NOM	MAX	
A	-	-	2.50	
A1	.40	.50	.60	
A2	1.12	1.17	1.22	
D		35.00 BSC		
D1		30.00 BSC		
E		35.00 BSC		
E1		30.00 BSC		
M		34 (DEPOPULATED)		3
N		525		4
e		1.00 BSC		
b	.50	.63	.70	5
c		.56 REF		
d		1.00 REF		
f		11.00 REF		
g		11.00 REF		
CENTER BALL MATRIX		5 X 9		

TOLERANCES UNLESS SPECIFIED		 Integrated Device Technology, Inc. 6025 Silver Creek Valley Road Fremont, CA 94538 PHONE: (408) 294-6500 FAX: (408) 294-6591
DECIMAL	ANGULAR	
±	±	
XXXX±	XXXX±	
APPROVALS	DATE	TITLE
DRAWN <i>gty</i>	05/05/02	BB/BBG 525 PACKAGE OUTLINE
CHECKED		35.0 X 35.0 mm BODY PBGA
		1.00 mm BALL PITCH
SIZE	DRAWING No.	REV
C	PSC-4112	02
DO NOT SCALE DRAWING		SHEET 2 OF 3


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	PRELIMINARY RELEASE	05/05/02	TU VU
01	ADDED GREEN BBG	06/22/09	P.Palk
02	COMBINE POD & LAND PATTERN	06/07/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		 Integrated Device Technology, Inc. 8025 Silver Creek Valley Road Fremont, CA 94538 PHONE: (408) 294-8200 FAX: (408) 294-8991
DECIMAL	ANGULAR	
XX±	±	
XXX±		
XXXX±		
APPROVALS	DATE	TITLE
DRAWN <i>gry</i>	05/05/02	BB/BBG 525 PACKAGE OUTLINE
CHECKED		35.0 X 35.0 mm BODY PBGA
		1.00 mm BALL PITCH
SIZE	DRAWING No.	REV
C	PSC-4112	02
DO NOT SCALE DRAWING		SHEET 3 OF 3